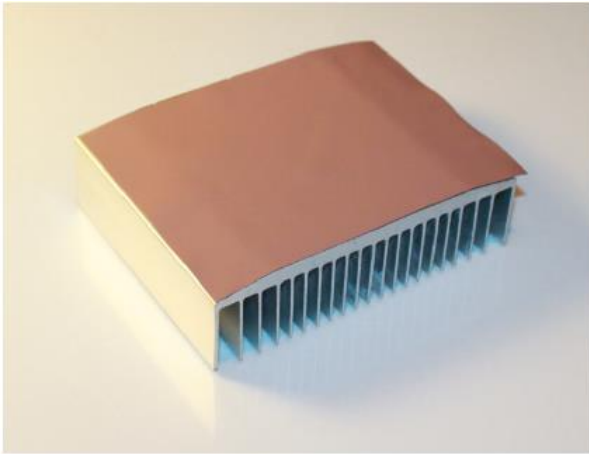


Datasheet

Interface for HS50

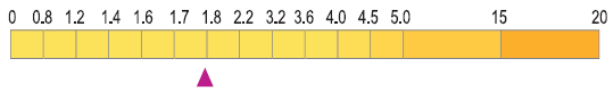
RS Stock number 758-0948



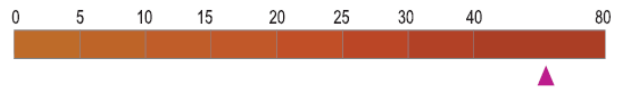
Specifications:

Property	H48-2K	Unit	Test Method
Thickness (+/- 10%)	0.1/0.2/0.3	mm	-
Color	Dark Red	-	Visual
Construction	Silicone based with ceramic fillers (non-silicone oil)	-	-
Opt.Temp. Range	-45 to 200	°C	-
Density	2.1	g/cm ³	ASTM D792
Thermal Conductivity	1.8	W/m.k	ASTM D5470
Hardness Shore A	60	-	ASTM D2240
Thermal impedance			ASTM D5470
10psi	0.21/0.37/0.57	K- in ² /W	-
50psi	0.20/0.33/0.51	K- in ² /W	-
100psi	0.17/0.31/0.46	K- in ² /W	-
Percent deflection			ASTM D575
10psi	2	%	-
50psi	5	%	-
100psi	11	%	-
Breakdown voltage	1.2 / 2.5 / 3.5	kV	ASTM D149
TML	< 0.5%	%	ASTM E595
Tensile strength	200	Psi	ASTM D412
Elongation	50	%	ASTM D412
UL flammability	V-0	-	UL 94

Thermal Conductivity: 1.8 W/m.k
(W / m.k - Z Axis)



Hardness: 60 (Shore A)
(Shore A)



In the thermal resistance vs pressure vs deflection charts H48-2K provides low thermal impedance.
As the pressure increases the thermal impedance decreases. H48-2K provides good compliance and softness.

Features

- No carrier
- Low contact thermal impedance
- Non-oil Bleed
- High dielectric breakdown voltage

Applications

- Electronic components: IC/CPU/MOS
- LED/ M/B / P/S / Heat Sink/LCD-TV/Notebook
PC/PC/Telecom Device
- Wireless Hub etc...
- DDR II Module/DVD Application/Hand-Set Applications etc...